ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company unic			ique ID	Unique I			nique ID Authority				Respon	Response Date*			
isemi											2024-05	2024-05-17			
ontact Name	Title - Contac	Title - Contact			Phone - Contact*				Email -	Email - Contact*					
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Represen			sentative	Phone - Representative*					Email - Representative*						
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Requester Item Number						Effective Da	ate V	ersion	Manu	facturing Site	Weight* UOM Unit T			Unit Type	
	AR043	430CSSC14SMR 4MP_1/3 CIS SO		)		2024-05-17			TA1			291.23		mg	Each
lanufacturing Proccess Informa	ition														
Terminal Plating / Grid Array M	aterial	Ferminal Base Alloy J		J-STD-020 MS	SL Rating	g Peak Pr		Process Body Temperature Max Time at Pea		ak Tempera	Temperature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no CU A Sn)		CU Alloy		4		260		C 30		0	secor	seconds 3			
omments															
or more information regarding material	composition	n please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	62.83	mg		Misc.	proprietary data		0.2388	mg
			Supplier	Silicon (Si)	7440-21-3		61.9692	mg
			Supplier	Aluminum (Al)	7429-90-5		0.622	mg
Die Attach	2.76	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		1.035	mg
			Supplier	Ethylene Glycol	107-21-1		0.0276	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0828	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.5796	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.035	mg
Imaging Lens	66.68	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.334	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.334	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.334	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.334	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3334	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.334	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.334	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		46.3426	mg
Lid Attach	2.87	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9069	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1492	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.9069	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9069	mg
Mold Compound-Black	59.52	mg		Phenolic Resin	proprietary data		8.928	mg
			Supplier	Oxirane	39817-09-9		8.928	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.7856	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5952	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.0928	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1904	mg
Substrate and Solder Mask	96.33	mg	Supplier	Acetophenone	98-86-2		1.8881	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		21.3756	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.2619	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.2716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3179	mg

				2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.3179	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.7761	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	9.633	mg
			Supplier	Copper (Cu)	7440-50-8	46.7201	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.7679	mg
Wire Bond - Au	0.24	mg	Supplier	Gold (Au)	7440-57-5	0.24	mg